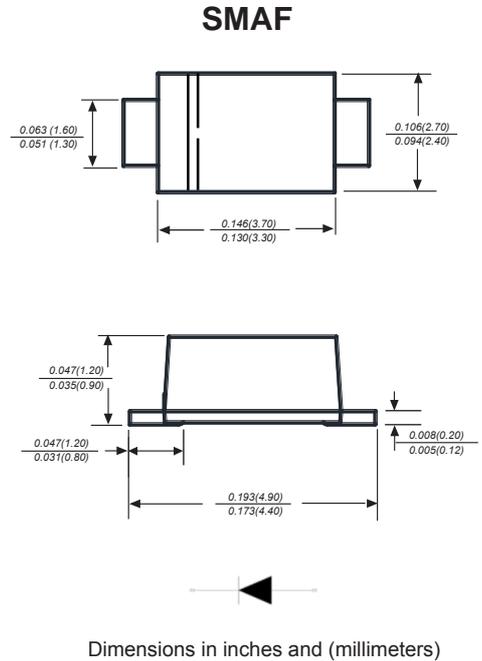


## FEATURES

1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
2. For surface mounted applications
3. Low reverse leakage
4. Built-in strain relief, ideal for automated placement
5. High forward surge current capability
6. High temperature soldering guaranteed:  
260°C/10 seconds at terminals  
Glass passivated chip junction

## MECHANICAL DATA

**Case** : JEDEC SMAF Molded plastic body  
**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity** : Polarity symbol marking on body  
**Mounting Position** : Any  
**Weight** : 0.0018 ounce, 0.064 grams



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	UNITS
Marking Code		ES1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=55^\circ C$	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	0.95			1.25		1.70		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ C$ $T_A=125^\circ C$	$I_R$	5.0 50							$\mu A$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	15.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	60.0							$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ C$

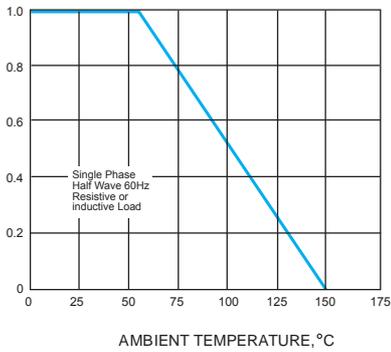
**Note:** 1. Reverse recovery condition  $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$   
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

# OTW<sup>®</sup> SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER ES1AF THRU ES1JF

## Ratings And Characteristic Curves

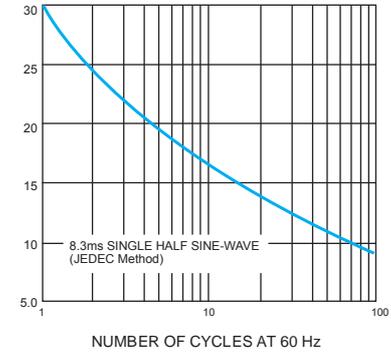
AVERAGE FORWARD RECTIFIED CURRENT,  
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



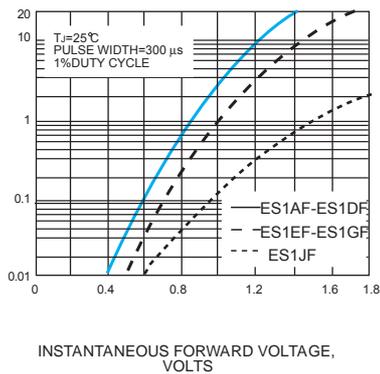
PEAK FORWARD SURGE CURRENT,  
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



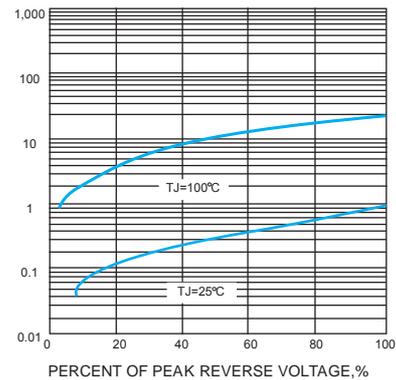
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



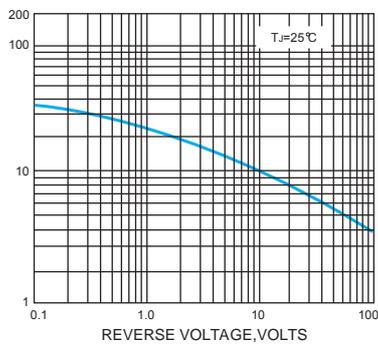
INSTANTANEOUS REVERSE CURRENT,  
MICROAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



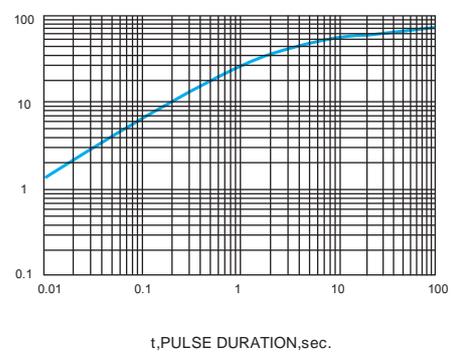
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



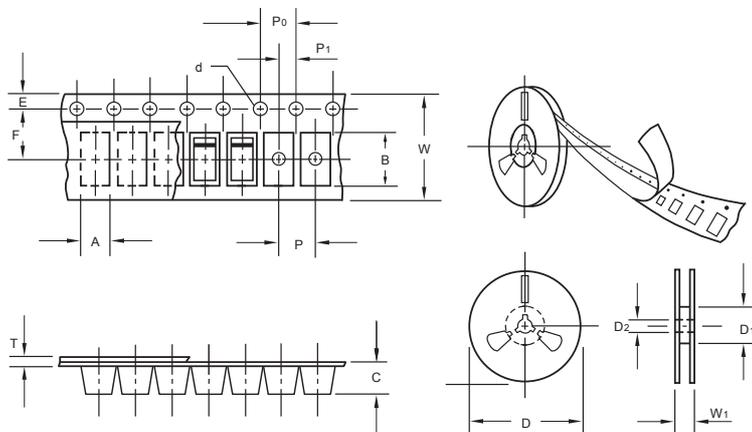
TRANSIENT THERMAL IMPEDANCE,  
°C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



# OTW<sup>®</sup> SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER ES1AF THRU ES1JF

## Packing information



unit:mm

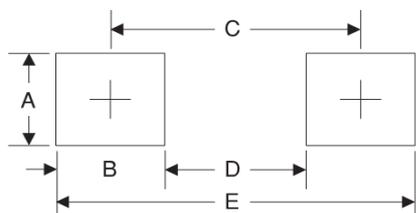
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D <sub>1</sub>	min	54.40
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213